



HF 212

solder paste



HARIMA MULTiCORE HF 212

With a greater number of electronics applications requiring the use of larger printed circuit boards which have associated inherent thermal demands, HARIMA MULTiCORE have developed a fully halogen-free solder paste for use in such industrial and automotive applications.

HARIMA MULTiCORE HF 212 is available in standard SAC and high reliability 90iSC solder alloys and is designed to encompass a wide process window with improved thermal, electrical, and mechanical connectivity. These solder paste solutions ensure outstanding performance in the most demanding high value PCB applications – all provided by a halogen-free formulation.

HALOGEN FREE

HF 212 ATTRIBUTES AND BENEFITS

PRODUCT ATTRIBUTE	PROCESS BENEFIT
HALOGEN-FREE	Harima Multicore HF212 solder paste meets all the current definitions of halide free and halogen-free: • No added halogen • Measured < 900 ppm chlorine and bromine and < 1500 ppm total by Oxygen Bomb test (J-STD-004B: EN14582) • Flux classification ROL0 in accordance with J-STD-004B
AVAILABILITY	Lead free solder alloys in both Type 3 and Type 4 particle size distributions: • Standard SAC (SAC305, SAC387) • High reliability 90iSC
APPLICATION	• Designed for stencil printing, excellent for pin-in-paste and enclosed head applications • Excellent wetting to a broad range of metallization • Compatible with existing halogen-free solutions • Suitable for medium and large PCB assemblies
PRINTING ADVANTAGES	• Wide process window for printing with fine pitch capability • Minimal slump and reduction of solder bridging • Suited for high throughput lines where yield consistency on print deposits is critical • Abandon time of up to 4 hours; work life > 8 hours
REFLOW ADVANTAGES	• Optimised for long soak reflow profiles • Improved fine pitch coalescence • Excellent humidity resistance • Excellent solderability on challenging surface finishes
LOW VOIDING	Low void levels increase solder joint reliability • New chemistry allows for low void levels (< 5 %) in ball joints (BGA, CSP) • Low voiding on multiple finishes (ENIG, OSP copper, CuNiZn, immersion silver)
RESIDUES	• Clear, colourless and transparent • Pin-testable • High reliability, meeting requirements of J-STD-004B for SIR and electromigration

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